PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Masato ISHIBASHI	04/27/2009
Katsuyuki HORITA	04/27/2009
Tomohiro YAMASHITA	04/27/2009
Takaaki TSUNOMURA	04/15/2009
Takashi KUROI	04/28/2009

RECEIVING PARTY DATA

Name:	RENESAS TECHNOLOGY CORP.	
Street Address:	6-2, Otemachi 2-chome	
City:	Chiyoda-ku, Tokyo	
State/Country:	JAPAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12495070

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: 067237-0554

NAME OF SUBMITTER: Stephen A. Becker

Total Attachments: 2

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PATENT REEL: 022895 FRAME: 0134 00 1249507

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PATENT REEL: 022895 FRAME: 0135

RECORDATION FORM	1 COVER SHEET			
Docket No.: 067237-0554 PATENTS ONLY				
To the Director of the U. S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.				
1. Name of Conveying Party(ies)	2. Name and address of receiving party(ies)			
Masato ISHIBASHI, Katsuyuki HORITA, Tomohiro	Name: RENESAS TECHNOLOGY CORP.			
YAMASHITA, Takaaki TSUNOMURA, Takashi KUROI				
,	Internal Address:			
Additional name(s) of conveying party(ies) attached? Yes No				
3. Nature of Conveyance/Execution Date(s)	Address: 6-2, Otemachi 2-chome, Chiyoda-ku, Tokyo			
•	JAPAN			
Execution Date(s): April 27, 2009, April 27, 2009, April 27,				
2009, April 15, 2009 and April 28, 2009				
(respectively)				
☐ Security Agreement ☐ Change of Name				
Joint Research Agreement				
Government Interest Assignment				
Executive Order 9424, Confirmatory License				
Other	Additional name(s) & address(es) attached? Yes No			
4. Application or patent number(s):	☐ This document is being filed together with a new application.			
A. Patent Application No(s).	B. Patent No(s).			
Additional numbers attac	hed? Yes No			
5. Name and address to whom correspondence concerning	6. Total number of applications and patents 1			
document should be mailed:	involved:			
Name: MCDERMOTT WILL & EMERY LLP	7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00			
Internal Address:	Authorized to be charged by credit card			
	Authorized to be charged to deposit account			
Street Address: 600 13th Street, N.W.	☐ Enclosed			
	None required (government interest not affecting title)			
City: Washington State: D. C. Zip: 20005-3096				
Phone Number: 202.756.8000	8. Payment Information:			
Fax Number: 202.756.8087				
Email Address:	a. Credit Card Last 4 Numbers Expiration Data			
	Expiration Date b. Deposit Account Number 500417			
	Authorized User Name			
9. Signature.	CMO 1 10001			
Stephen A. Becker 26,527 Semand Cold (By. No. 46,429) for June 30, 2009				
Name and Registration No. of Person Signing	Signature Date			
Total number of pages including cover sheet, attachments and documents: 2				

PATENT REEL: 022895 FRAME: 0136

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Technology Corp.,

a corporation organized under the laws of Japan,

located at 6-2, Otemachi 2-chome, Chiyoda-ku, Tokyo, Japan,

receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Technology Corp., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Renesas Technology Corp.,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Technology Corp.

Signed on the date(s) indicated aside our signatures:

RECORDED: 06/30/2009

INVENTOR(S)

(発明者フルネームサイン)	(署名日)
1) Masato Ishibashi Masato Ishibashi	27/Aprol /2009
2) Katsuyubi Horita Katsuyuki HORITA	27/April/2009
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4) Takaaki Tsunomura Takaaki TSUNOMURA	15/Apr;1/2009
5) Jakosh Kure Takashi KUROI	28/April /2009
6)	
7)	· · · · · · · · · · · · · · · · · · ·
8)	·
9)	·
10)	

PAIENI

Date Signed

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